

**256K x 16 Static RAM**

**Features**

- **Temperature Ranges**
  - Commercial: 0°C to 70°C
  - Industrial: -40°C to 85°C
  - Automotive-A: -40°C to 85°C
- **High speed**
  - $t_{AA} = 15 \text{ ns}$
- **Low active power**
  - 1540 mW (max.)
- **Low CMOS standby power (L version)**
  - 2.75 mW (max.)
- **2.0V Data Retention (400  $\mu\text{W}$  at 2.0V retention)**
- **Automatic power-down when deselected**
- **TTL-compatible inputs and outputs**
- **Easy memory expansion with  $\overline{\text{CE}}$  and  $\overline{\text{OE}}$  features**
- **Available in Pb-free and non Pb-free 44-pin TSOP II and molded 44-pin (400-Mil) SOJ packages**

**Functional Description**

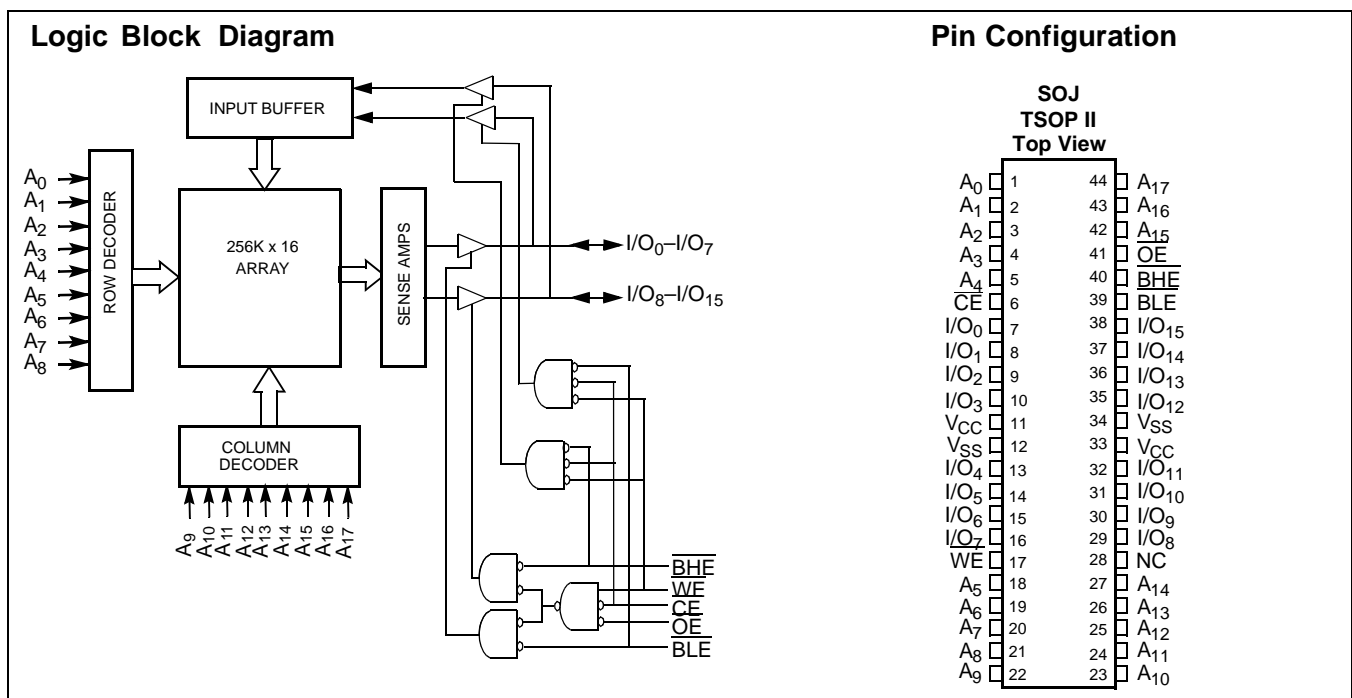
The CY7C1041BN is a high-performance CMOS static RAM organized as 262,144 words by 16 bits.

Writing to the device is accomplished by taking Chip Enable ( $\overline{\text{CE}}$ ) and Write Enable ( $\overline{\text{WE}}$ ) inputs LOW. If Byte Low Enable ( $\overline{\text{BLE}}$ ) is LOW, then data from I/O pins (I/O<sub>0</sub> through I/O<sub>7</sub>), is written into the location specified on the address pins (A<sub>0</sub> through A<sub>17</sub>). If Byte High Enable ( $\overline{\text{BHE}}$ ) is LOW, then data from I/O pins (I/O<sub>8</sub> through I/O<sub>15</sub>) is written into the location specified on the address pins (A<sub>0</sub> through A<sub>17</sub>).

Reading from the device is accomplished by taking Chip Enable ( $\overline{\text{CE}}$ ) and Output Enable ( $\overline{\text{OE}}$ ) LOW while forcing the Write Enable ( $\overline{\text{WE}}$ ) HIGH. If Byte Low Enable ( $\overline{\text{BLE}}$ ) is LOW, then data from the memory location specified by the address pins will appear on I/O<sub>0</sub> to I/O<sub>7</sub>. If Byte High Enable ( $\overline{\text{BHE}}$ ) is LOW, then data from memory will appear on I/O<sub>8</sub> to I/O<sub>15</sub>. See the truth table at the back of this data sheet for a complete description of read and write modes.

The input/output pins (I/O<sub>0</sub> through I/O<sub>15</sub>) are placed in a high-impedance state when the device is deselected ( $\overline{\text{CE}}$  HIGH), the outputs are disabled ( $\overline{\text{OE}}$  HIGH), the  $\overline{\text{BHE}}$  and  $\overline{\text{BLE}}$  are disabled ( $\overline{\text{BHE}}$ ,  $\overline{\text{BLE}}$  HIGH), or during a write operation ( $\overline{\text{CE}}$  LOW, and  $\overline{\text{WE}}$  LOW).

The CY7C1041BN is available in a standard 44-pin 400-mil-wide body width SOJ and 44-pin TSOP II package with center power and ground (revolutionary) pinout.



**Selection Guide**

		-15	-20	Unit
Maximum Access Time		15	20	ns
Maximum Operating Current	Commercial	190	170	mA
	Industrial	210	190	
	Automotive-A		190	
Maximum CMOS Standby Current	Commercial	3	3	mA
	Commercial   L	0.5	0.5	
	Industrial	6	6	
	Automotive-A		6	

**Maximum Ratings**

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature ..... -65°C to +150°C  
 Ambient Temperature with Power Applied ..... -55°C to +125°C  
 Supply Voltage on V<sub>CC</sub> to Relative GND<sup>[1]</sup> .... -0.5V to +7.0V  
 DC Voltage Applied to Outputs in High Z State<sup>[1]</sup> ..... -0.5V to V<sub>CC</sub> + 0.5V

DC Input Voltage<sup>[1]</sup> ..... -0.5V to V<sub>CC</sub> + 0.5V  
 Current into Outputs (LOW) ..... 20 mA

**Operating Range**

Range	Ambient Temperature <sup>[2]</sup>	V <sub>CC</sub>
Commercial	0°C to +70°C	5V ± 0.5
Industrial	-40°C to +85°C	
Automotive-A	-40°C to +85°C	

**Electrical Characteristics** Over the Operating Range

Parameter	Description	Test Conditions	-15		-20		Unit
			Min.	Max.	Min.	Max.	
V <sub>OH</sub>	Output HIGH Voltage	V <sub>CC</sub> = Min., I <sub>OH</sub> = -4.0 mA	2.4		2.4		V
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> = Min., I <sub>OL</sub> = 8.0 mA		0.4		0.4	V
V <sub>IH</sub>	Input HIGH Voltage		2.2	V <sub>CC</sub> + 0.5	2.2	V <sub>CC</sub> + 0.5	V
V <sub>IL</sub>	Input LOW Voltage <sup>[1]</sup>		-0.5	0.8	-0.5	0.8	V
I <sub>IX</sub>	Input Load Current	GND ≤ V <sub>I</sub> ≤ V <sub>CC</sub>	-1	+1	-1	+1	mA
I <sub>OZ</sub>	Output Leakage Current	GND ≤ V <sub>OUT</sub> ≤ V <sub>CC</sub> , Output Disabled	-1	+1	-1	+1	mA
I <sub>CC</sub>	V <sub>CC</sub> Operating Supply Current	V <sub>CC</sub> = Max., f = f <sub>MAX</sub> = 1/t <sub>RC</sub>	Comm'l	190		170	mA
			Ind'l	210		190	mA
			Auto-A			190	mA
I <sub>SB1</sub>	Automatic CE Power-Down Current—TTL Inputs	Max. V <sub>CC</sub> , CE ≥ V <sub>IH</sub> , V <sub>IN</sub> ≥ V <sub>IH</sub> or V <sub>IN</sub> ≤ V <sub>IL</sub> , f = f <sub>MAX</sub>		40		40	mA
I <sub>SB2</sub>	Automatic CE Power-Down Current—CMOS Inputs	Max. V <sub>CC</sub> , CE ≥ V <sub>CC</sub> - 0.3V, V <sub>IN</sub> ≥ V <sub>CC</sub> - 0.3V, or V <sub>IN</sub> ≤ 0.3V, f = 0	Comm'l	3		3	mA
			Comm'l   L	0.5		0.5	mA
			Ind'l	6		6	mA
			Auto-A			6	mA

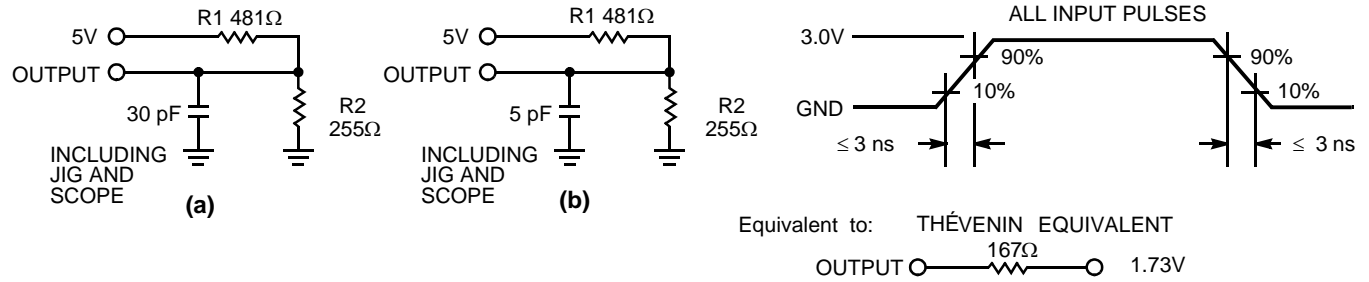
**Notes:**

- V<sub>IL</sub> (min.) = -2.0V for pulse durations of less than 20 ns.
- T<sub>A</sub> is the case temperature.
- Tested initially and after any design or process changes that may affect these parameters.

**Capacitance<sup>[3]</sup>**

Parameter	Description	Test Conditions	Max.	Unit
C <sub>IN</sub>	Input Capacitance	T <sub>A</sub> = 25°C, f = 1 MHz, V <sub>CC</sub> = 5.0V	8	pF
C <sub>OUT</sub>	I/O Capacitance		8	pF

**AC Test Loads and Waveforms**



**Switching Characteristics<sup>[4]</sup> Over the Operating Range**

Parameter	Description	-15		-20		Unit
		Min.	Max.	Min.	Max.	
<b>Read Cycle</b>						
t <sub>power</sub>	V <sub>CC</sub> (typical) to the First Access <sup>[5]</sup>	1		1		μs
t <sub>RC</sub>	Read Cycle Time	15		20		ns
t <sub>AA</sub>	Address to Data Valid		15		20	ns
t <sub>OHA</sub>	Data Hold from Address Change	3		3		ns
t <sub>ACE</sub>	$\overline{CE}$ LOW to Data Valid		15		20	ns
t <sub>DOE</sub>	$\overline{OE}$ LOW to Data Valid		7		8	ns
t <sub>LZOE</sub>	$\overline{OE}$ LOW to Low Z	0		0		ns
t <sub>HZOE</sub>	$\overline{OE}$ HIGH to High Z <sup>[6, 7]</sup>		7		8	ns
t <sub>LZCE</sub>	$\overline{CE}$ LOW to Low Z <sup>[7]</sup>	3		3		ns
t <sub>HZCE</sub>	$\overline{CE}$ HIGH to High Z <sup>[6, 7]</sup>		7		8	ns
t <sub>PU</sub>	$\overline{CE}$ LOW to Power-Up	0		0		ns
t <sub>PD</sub>	$\overline{CE}$ HIGH to Power-Down		15		20	ns
t <sub>DBE</sub>	Byte Enable to Data Valid		7		8	ns
t <sub>LZBE</sub>	Byte Enable to Low Z	0		0		ns
t <sub>HZBE</sub>	Byte Disable to High Z		7		8	ns

**Notes:**

- Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I<sub>OL</sub>/I<sub>OH</sub> and 30-pF load capacitance.
- This part has a voltage regulator which steps down the voltage from 5V to 3.3V internally. t<sub>power</sub> time has to be provided initially before a read/write operation is started.
- t<sub>HZOE</sub>, t<sub>HZCE</sub>, and t<sub>HZWE</sub> are specified with a load capacitance of 5 pF as in part (b) of AC Test Loads. Transition is measured ±500 mV from steady-state voltage.
- At any given temperature and voltage condition, t<sub>HZCE</sub> is less than t<sub>LZCE</sub>, t<sub>HZOE</sub> is less than t<sub>LZOE</sub>, and t<sub>HZWE</sub> is less than t<sub>LZWE</sub> for any given device.

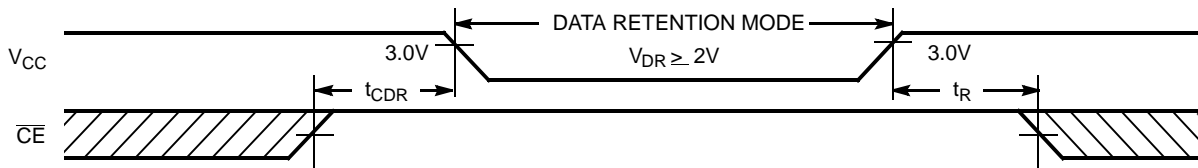
**Switching Characteristics**<sup>[4]</sup> Over the Operating Range (continued)

Parameter	Description	-15		-20		Unit
		Min.	Max.	Min.	Max.	
<b>Write Cycle</b> <sup>[8, 9]</sup>						
t <sub>WC</sub>	Write Cycle Time	15		20		ns
t <sub>SCE</sub>	CE LOW to Write End	12		13		ns
t <sub>AW</sub>	Address Set-Up to Write End	12		13		ns
t <sub>HA</sub>	Address Hold from Write End	0		0		ns
t <sub>SA</sub>	Address Set-Up to Write Start	0		0		ns
t <sub>PWE</sub>	WE Pulse Width	12		13		ns
t <sub>SD</sub>	Data Set-Up to Write End	8		9		ns
t <sub>HD</sub>	Data Hold from Write End	0		0		ns
t <sub>LZWE</sub>	WE HIGH to Low Z <sup>[7]</sup>	3		3		ns
t <sub>HZWE</sub>	WE LOW to High Z <sup>[6, 7]</sup>		7		8	ns
t <sub>BW</sub>	Byte Enable to End of Write	12		13		ns

**Data Retention Characteristics** Over the Operating Range (L version only)

Parameter	Description	Conditions <sup>[11]</sup>	Min.	Max.	Unit
V <sub>DR</sub>	V <sub>CC</sub> for Data Retention		2.0		V
I <sub>CCDR</sub>	Data Retention Current	V <sub>CC</sub> = V <sub>DR</sub> = 2.0V, CE ≥ V <sub>CC</sub> - 0.3V, V <sub>IN</sub> ≥ V <sub>CC</sub> - 0.3V or V <sub>IN</sub> ≤ 0.3V		200	μA
t <sub>CDR</sub> <sup>[3]</sup>	Chip Deselect to Data Retention Time		0		ns
t <sub>R</sub> <sup>[10]</sup>	Operation Recovery Time		t <sub>RC</sub>		ns

**Data Retention Waveform**

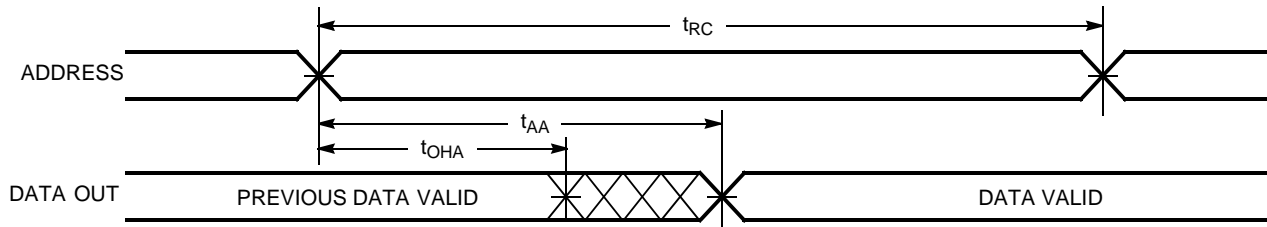


**Notes:**

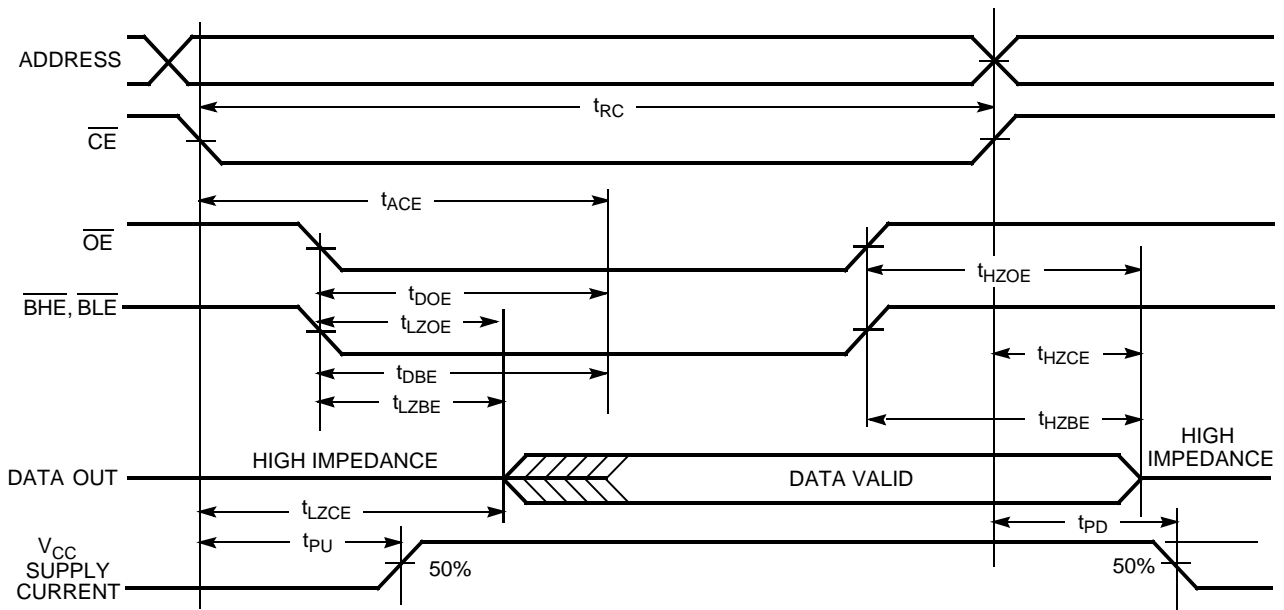
- 8. The internal write time of the memory is defined by the overlap of CE LOW, and WE LOW. CE and WE must be LOW to initiate a write, and the transition of either of these signals can terminate the write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the write.
- 9. The minimum write cycle time for Write Cycle no. 3 (WE controlled, OE LOW) is the sum of t<sub>HZWE</sub> and t<sub>SD</sub>.
- 10. t<sub>r</sub> ≤ 3 ns for the -15 speed. t<sub>r</sub> ≤ 5 ns for the -20 and slower speeds.
- 11. No input may exceed V<sub>CC</sub> + 0.5V.

### Switching Waveforms

#### Read Cycle No. 1<sup>[12, 13]</sup>



#### Read Cycle No. 2 ( $\overline{OE}$ Controlled)<sup>[13, 14]</sup>

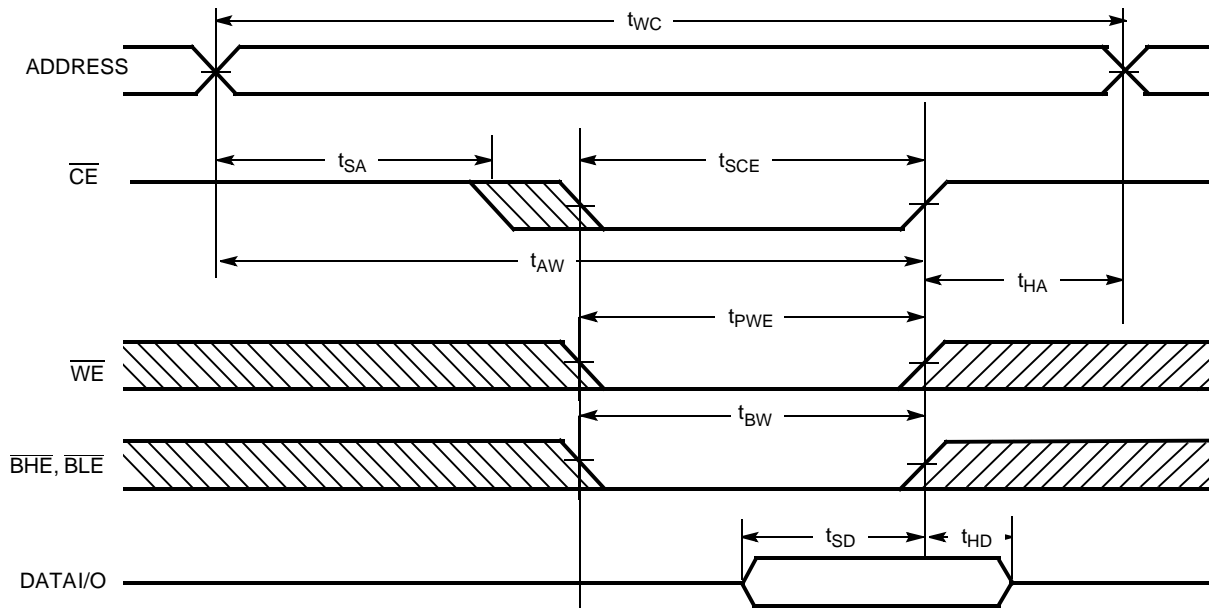


**Notes:**

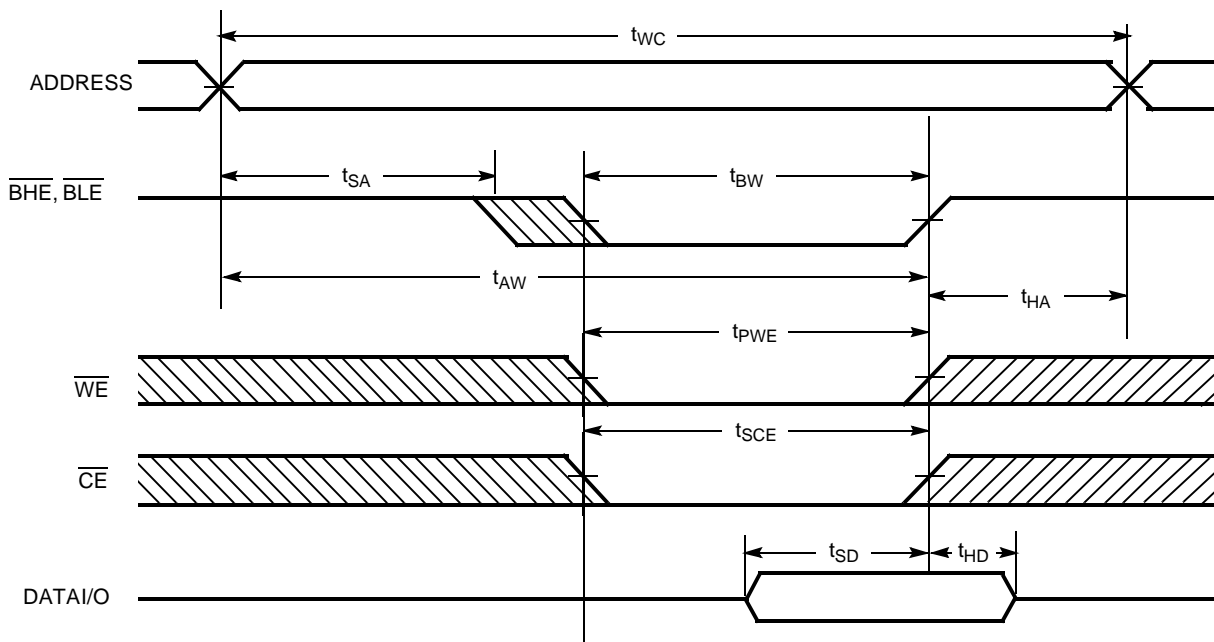
- 12. Device is continuously selected.  $\overline{OE}$ ,  $\overline{CE}$ ,  $\overline{BHE}$ , and/or  $\overline{BLE}$  =  $V_{IL}$ .
- 13.  $\overline{WE}$  is HIGH for read cycle.
- 14. Address valid prior to or coincident with  $\overline{CE}$  transition LOW.

Switching Waveforms (continued)

Write Cycle No. 1 ( $\overline{CE}$  Controlled)<sup>[15, 16]</sup>



Write Cycle No. 2 ( $\overline{BLE}$  or  $\overline{BHE}$  Controlled)

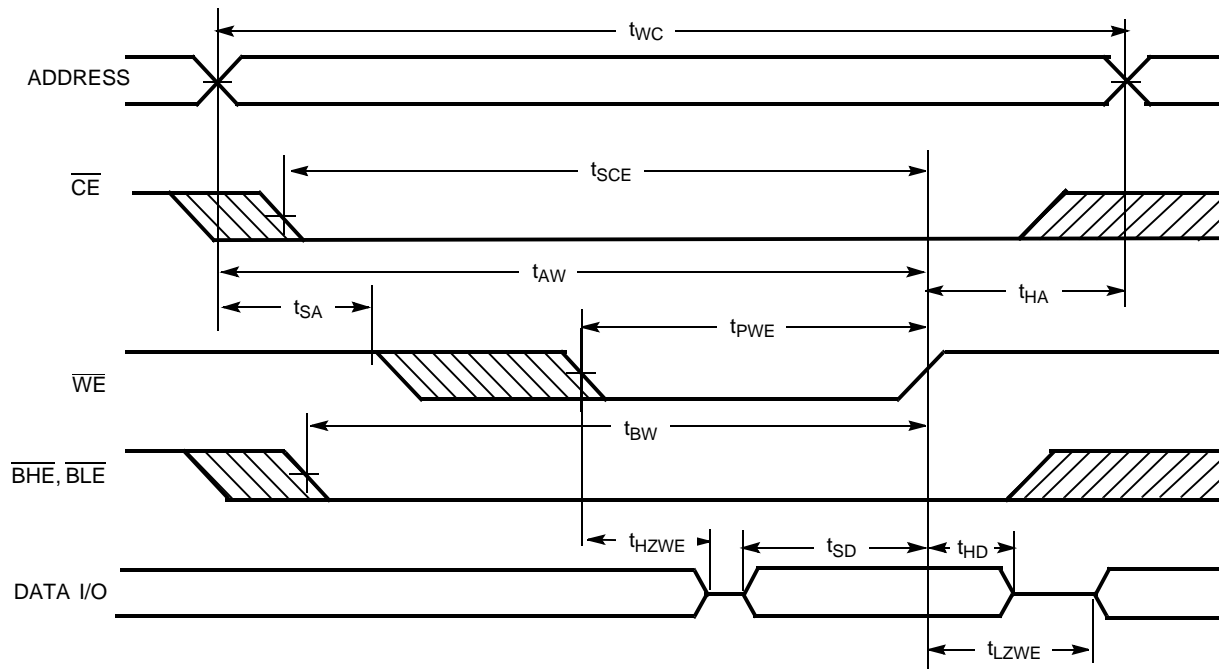


Notes:

- 15. Data I/O is high impedance if  $\overline{OE}$  or  $\overline{BHE}$  and/or  $\overline{BLE} = V_{IH}$ .
- 16. If  $\overline{CE}$  goes HIGH simultaneously with  $\overline{WE}$  going HIGH, the output remains in a high-impedance state.

Switching Waveforms (continued)

Write Cycle No. 3 ( $\overline{WE}$  Controlled,  $\overline{OE}$  LOW)



Truth Table

$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	$\overline{BLE}$	$\overline{BHE}$	I/O <sub>0</sub> -I/O <sub>7</sub>	I/O <sub>8</sub> -I/O <sub>15</sub>	Mode	Power
H	X	X	X	X	High Z	High Z	Power Down	Standby ( $I_{SB}$ )
L	L	H	L	L	Data Out	Data Out	Read All bits	Active ( $I_{CC}$ )
L	L	H	L	H	Data Out	High Z	Read Lower bits only	Active ( $I_{CC}$ )
L	L	H	H	L	High Z	Data Out	Read Upper bits only	Active ( $I_{CC}$ )
L	X	L	L	L	Data In	Data In	Write All bits	Active ( $I_{CC}$ )
L	X	L	L	H	Data In	High Z	Write Lower bits only	Active ( $I_{CC}$ )
L	X	L	H	L	High Z	Data In	Write Upper bits only	Active ( $I_{CC}$ )
L	H	H	X	X	High Z	High Z	Selected, Outputs Disabled	Active ( $I_{CC}$ )

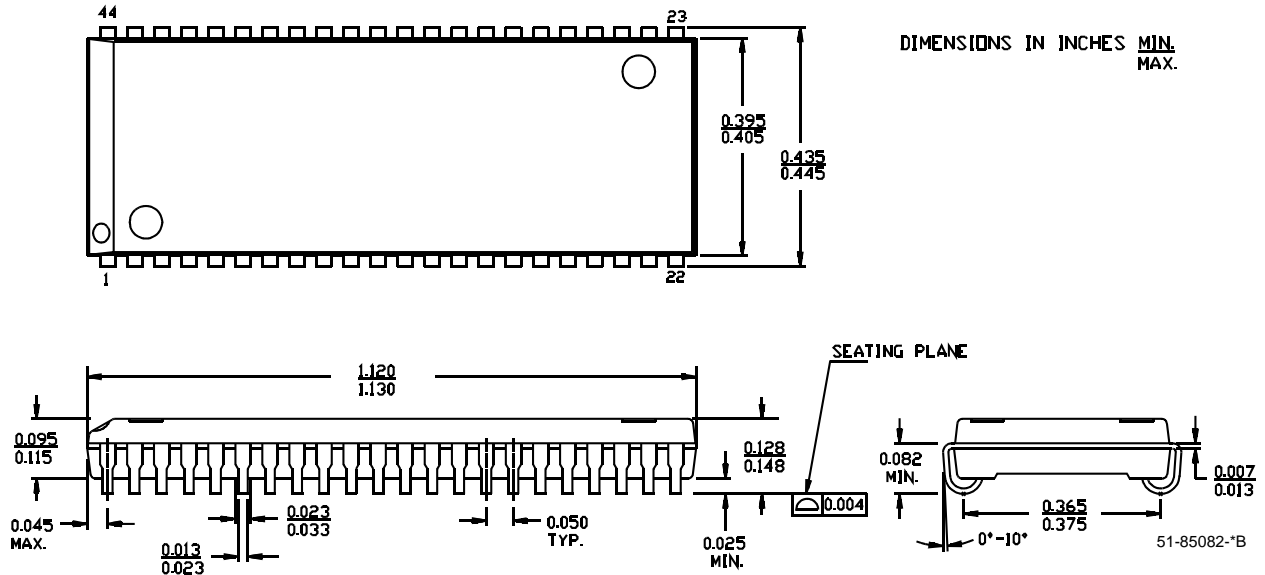
**Ordering Information**

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range	
15	CY7C1041BN-15VC	51-85082	44-pin (400-Mil) Molded SOJ	Commercial	
	CY7C1041BN-15VXC		44-pin (400-Mil) Molded SOJ (Pb-free)		
	CY7C1041BN-15ZC	51-85087	44-pin TSOP Type II		
	CY7C1041BN-15ZXC		44-pin TSOP Type II (Pb-free)		
	CY7C1041BNL-15ZC		44-pin TSOP Type II		
	CY7C1041BNL-15ZXC		44-pin TSOP Type II (Pb-free)		
	CY7C1041BN-15ZI		44-pin TSOP Type II		
	CY7C1041BN-15ZXI		44-pin TSOP Type II (Pb-free)		
	CY7C1041BN-15VI	51-85082	44-pin (400-Mil) Molded SOJ		Industrial
	CY7C1041BN-15VXI		44-pin (400-Mil) Molded SOJ (Pb-free)		
20	CY7C1041BN-20VXC	51-85082	44-pin (400-Mil) Molded SOJ (Pb-free)	Commercial	
	CY7C1041BNL-20VXC		44-pin (400-Mil) Molded SOJ (Pb-free)		
	CY7C1041BN-20ZC	51-85087	44-pin TSOP Type II		
	CY7C1041BN-20ZXC		44-pin TSOP Type II (Pb-free)		
	CY7C1041BN-20ZI		44-pin TSOP Type II		
	CY7C1041BN-20ZXI		44-pin TSOP Type II (Pb-free)		
	CY7C1041BN-20VXI	51-85082	44-pin (400-Mil) Molded SOJ (Pb-free)	Industrial	
	CY7C1041BN-20ZSXA	51-85087	44-pin TSOP Type II		Automotive-A

Please contact local sales representative regarding availability of these parts.

**Package Diagrams**

**44-pin (400-Mil) Molded SOJ (51-85082)**

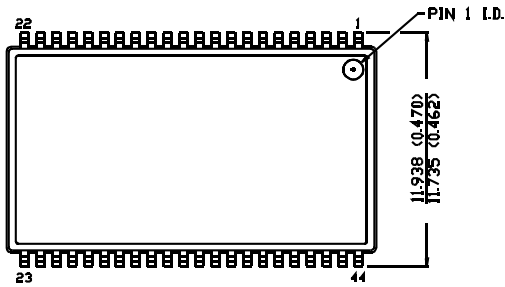




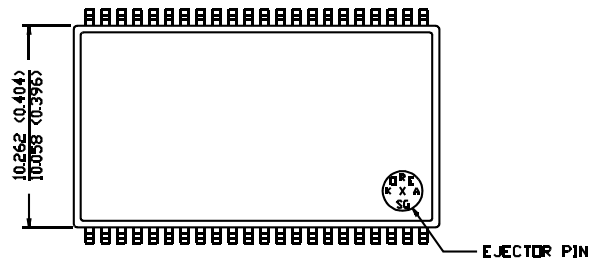
Package Diagrams (continued)

44-Pin TSOP II (51-85087)

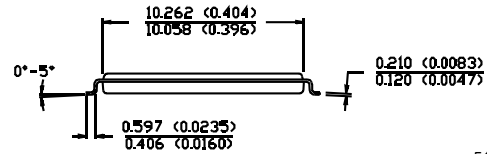
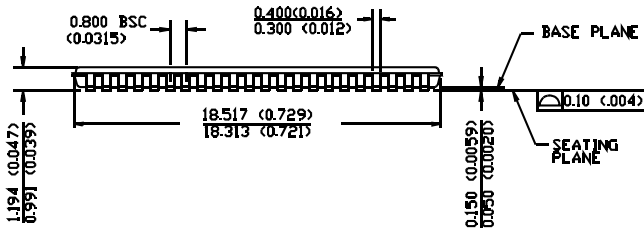
DIMENSION IN MM (INCH)  
MAX  
MIN



TOP VIEW



BOTTOM VIEW



51-85087-\*A

All products and company names mentioned in this document may be the trademarks of their respective holders.

**Document History Page**

<b>Document Title: CY7C1041BN 256K x 16 Static RAM</b> <b>Document Number: 001-06496</b>				
<b>REV.</b>	<b>ECN NO.</b>	<b>Issue Date</b>	<b>Orig. of Change</b>	<b>Description of Change</b>
**	424111	See ECN	NXR	New Data Sheets
*A	498575	See ECN	NXR	Added Automotive-A operating range updated Ordering Information Table